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ABSTRACT

DIE BONDING SHEET STICKING APPARATUS AND METHOD OF STICKING
DIE BONDING SHEET

Prior to sticking of a die bonding sheet comprising
a release sheet and a base provided with heat-sensitive
adhesive layer to a back surface of wafer, there is performed
5 not only cutting only the base provided with heat-sensitive
adhesive layer of the die bonding sheet in conformity with
an outline of the wafer, but also cutting the base provided
with heat-sensitive adhesive layer in the direction of a
width of the die bonding sheet with a spacing of given distance
10 from a rear end portion of the wafer in the direction of
carry of the wafer so as to form a leaf portion. Thereafter,
only the leaf portion corresponding to portion outside the
outline of the wafer is detached. The present invention
provides a die bonding sheet sticking apparatus and a method
15 of sticking a die bonding sheet which, in the process for
producing small electronic components, for example,
semiconductor chips, effect sticking to a back surface of
wafer a die bonding sheet capable of functioning not only
as a protective tape at the time of dicing but also as an
20 adhesive for die bonding at the time of die bonding of
semiconductor chips after dicing onto a lead frame.

(FIG.1)